





X2 ONE-DAY BLUNDELL TECH EVENT

Why Rework? The reasons for rework on electronic assemblies are as varied as the electronics themselves:

- There is a defect in the component.
- The wrong component has been assembled.
- The component was assembled in the wrong orientation.
- For Prototyping, cross change or failure analysis

These issues are your daily business?

Let's have a look into these issues together during the Rework TechEvent on 12 and 13 March.

Special Focus Topics

- Scavenging non-contact removal of residual solder
- Dip & Print Process: Which one is best for your applications - flux or paste?

We shall round-off the day with a hands-on session with Ersa rework systems. You are invited to bring along your assemblies for this.

Venue:

Unit C-D. Ouinn Close Seven Stars Industrial Estate Coventry, CV3 4LH

Speakers:

Blundell: Mark Cole, Keith Gummer

Ersa GmbH: Martin Dosch TEMPLE4: Nick Hirst.

Registration:

e-mail to: sales@blundell.co.uk

Participation:

The seminar includes refreshments, coffee, snacks and lunch. Please note that this seminar is held free of charge. There are no registration fees involved.



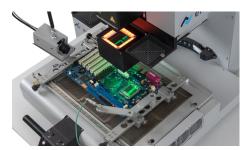


Agenda

12 | 13 March 2024







09:45 - 10:15	Arrival & Registration
10:15 – 10:30	Welcome Mark Cole & Keith Gummer, Blundell
11:30 - 11:00	SMT/BGA Rework - Technology Update Dip & Print - Flux or Solder Paste? Martin Dosch, Ersa GmbH
11:00 – 11:15	Coffee Break Get together. Networking. Exchange of Experience
11:15 – 12:00	SMT/BGA Rework - New Features Scavenging: Non-Contact solder removal Twin Nozzle Desoldering: Removing two components in one process Martin Dosch, Ersa GmbH
12:00 – 13:00	Lunch Get together. Networking. Exchange of Experience
13:00 – 15:00	Hands-On: SMT/BGA Treatment with different Rework Systems including Scavenging Dip & Print Martin Dosch, Ersa GmbH
15:00	Q&A and Good-bye Mark Cole & Keith Gummer, Blundell







